

74ALVC374

Octal D-type flip-flop; positive-edge trigger; 3-state

Rev. 02 — 17 October 2007

Product data sheet

1. General description

The 74ALVC374 is an octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-state outputs for bus-oriented applications. A clock input (CP) and an outputs enable input ($\overline{OE}$) are common to all flip-flops.

The eight flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW to HIGH CP transition.

When pin $\overline{OE}$ is LOW, the contents of the eight flip-flops is available at the outputs. When pin $\overline{OE}$ is HIGH, the outputs go to the high-impedance OFF-state. Operation of the $\overline{OE}$ input does not affect the state of the flip-flops.

The 74ALVC374 is functionally identical to the 74ALVC574, but has a different pin arrangement.

2. Features

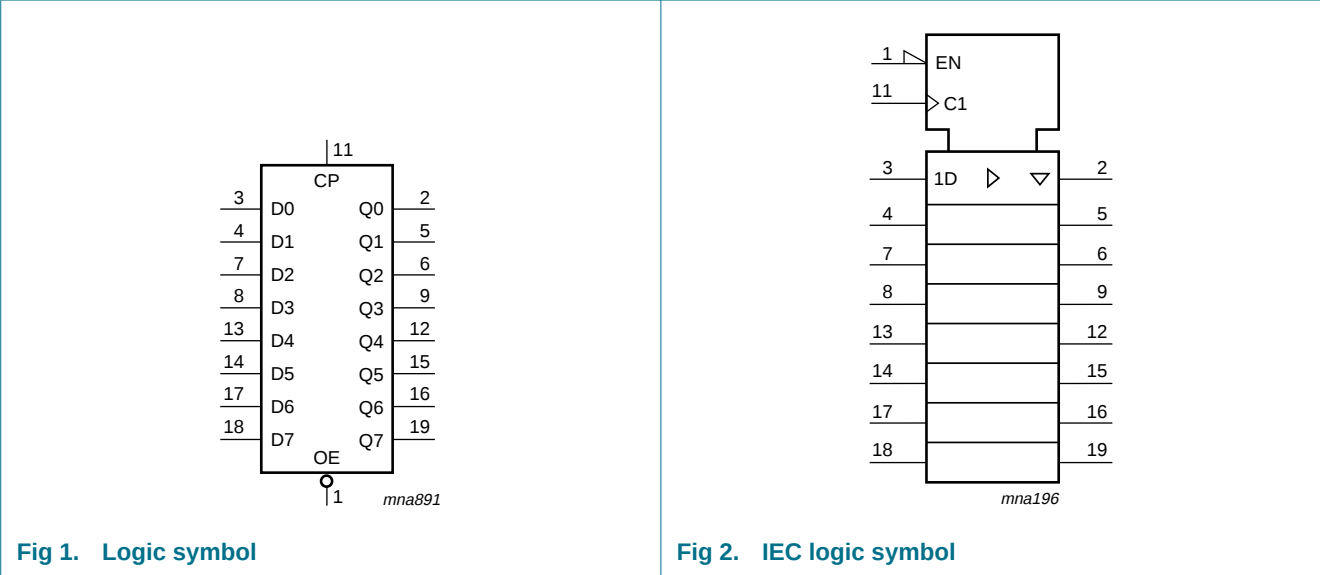
- Wide supply voltage range from 1.65 V to 3.6 V
- 3.6 V tolerant inputs/outputs
- CMOS low power consumption
- Direct interface with TTL levels (2.7 V to 3.6 V)
- Power-down mode
- Latch-up performance exceeds 250 mA
- Complies with JEDEC standards:
 - ◆ JESD8-7 (1.65 V to 1.95 V)
 - ◆ JESD8-5 (2.3 V to 2.7 V)
 - ◆ JESD8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A 115-A exceeds 200 V

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ALVC374D	−40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74ALVC374PW	−40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74ALVC374BQ	−40 °C to +85 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram



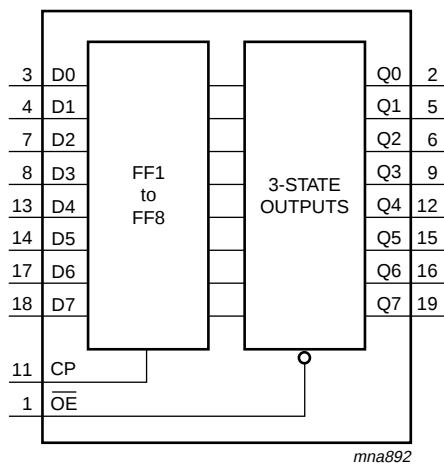


Fig 3. Functional diagram

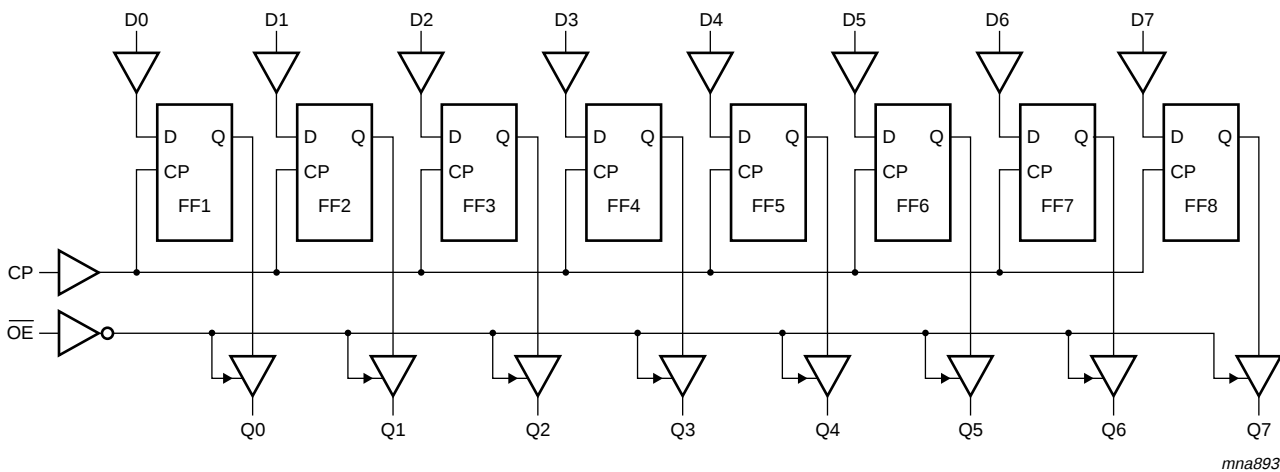
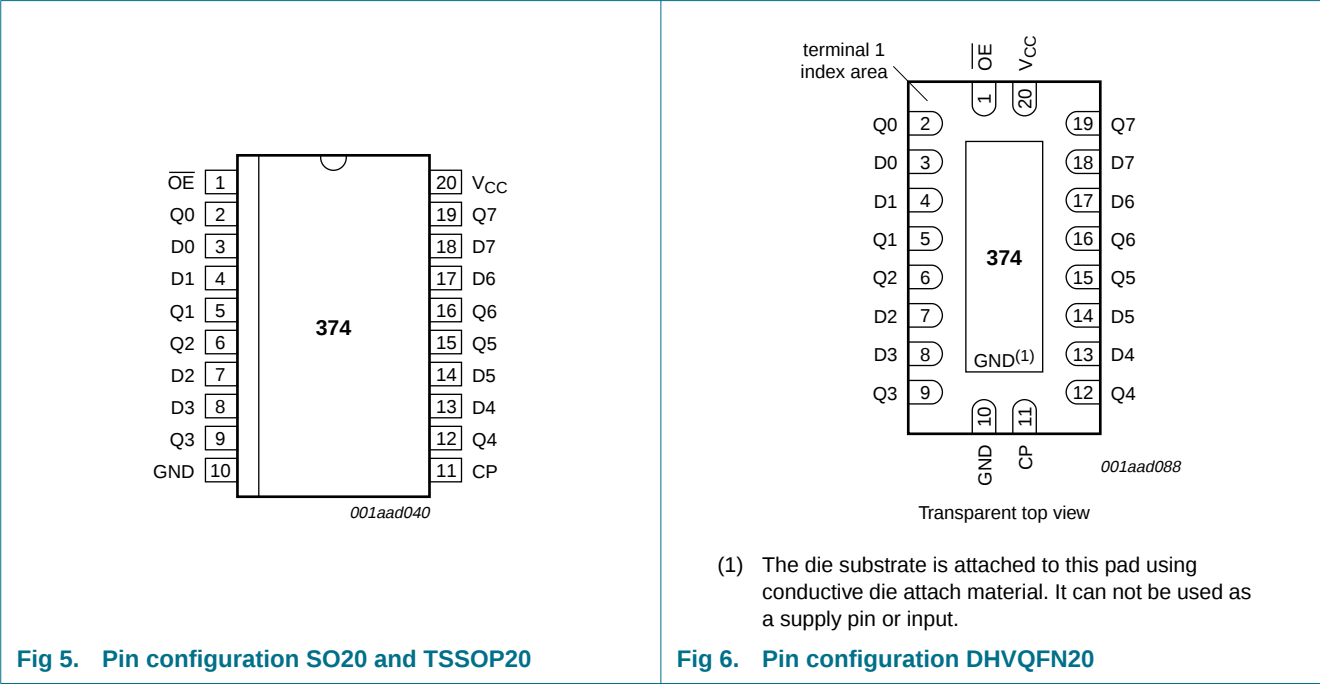


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
D[0:7]	3, 4, 7, 8, 13, 14, 17, 18	data input
CP	11	clock input (LOW to HIGH, edge-triggered)
OE	1	output enable input (active LOW)
Q[0:7]	2, 5, 6, 9, 12, 15, 16, 19	3-state flip-flop output
V _{CC}	20	supply voltage
GND	10	ground (0 V)

6. Functional description

Table 3. Function table^[1]

Operating mode	Input			Internal flip-flop	Output Qn
	OE	CP	Dn		
Load and read register	L	↑	l	L	L
	L	↑	h	H	H
Load register and disable outputs	H	↑	l	L	Z
	H	↑	h	H	Z

- [1] H = HIGH voltage level
 h = HIGH voltage level one set-up time prior to the LOW to HIGH CP transition
 L = LOW voltage level
 l = LOW voltage level one set-up time prior to the LOW to HIGH CP transition
 Z = high-impedance OFF-state
 ↑ = LOW to HIGH clock transition

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		−0.5	+4.6	V
I _{IK}	input clamping current	V _I < 0 V	−50	-	mA
V _I	input voltage		−0.5	+4.6	V
I _{OK}	output clamping current	V _O > V _{CC} or V _O < 0 V	-	±50	mA
V _O	output voltage	output HIGH or LOW state ^{[1] [2]}	−0.5	V _{CC} + 0.5	V
		output 3-state	−0.5	+4.6	V
		power-down mode, V _{CC} = 0 V ^[2]	−0.5	+4.6	V
I _O	output current	V _O = 0 V to V _{CC}	-	±50	mA
I _{CC}	supply current		-	100	mA
I _{GND}	ground current		−100	-	mA
T _{stg}	storage temperature		−65	+150	°C
P _{tot}	total power dissipation	T _{amb} = −40 °C to +85 °C ^[3]	-	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 [2] When V_{CC} = 0 V (power-down mode), the output voltage can be 3.6 V in normal operation.
 [3] For SO20 packages: above 70 °C derate linearly with 8 mW/K.
 For TSSOP20 packages: above 60 °C derate linearly with 5.5 mW/K.
 For DHVQFN20 packages: above 60 °C derate linearly with 4.5 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		1.65	3.6	V
V _I	input voltage		0	3.6	V
V _O	output voltage	output HIGH or LOW state	0	V _{CC}	V
		output 3-state	0	3.6	V
		power-down mode; V _{CC} = 0 V	0	3.6	V
T _{amb}	ambient temperature	in free air	−40	+85	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 1.65 V to 2.7 V	-	20	ns/V
		V _{CC} = 2.7 V to 3.6 V	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	−40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	-	-	V
		V _{CC} = 2.3 V to 2.7 V	1.7	-	-	V
		V _{CC} = 2.7 V to 3.6 V	2.0	-	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	-	-	0.7	V
		V _{CC} = 2.7 V to 3.6 V	-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = −100 μA; V _{CC} = 1.65 V to 3.6 V	V _{CC} − 0.2	-	-	V
		I _O = −6 mA; V _{CC} = 1.65 V	1.25	1.51	-	V
		I _O = −12 mA; V _{CC} = 2.3 V	1.8	2.10	-	V
		I _O = −18 mA; V _{CC} = 2.3 V	1.7	2.01	-	V
		I _O = −12 mA; V _{CC} = 2.7 V	2.2	2.53	-	V
		I _O = −18 mA; V _{CC} = 3.0 V	2.4	2.76	-	V
		I _O = −24 mA; V _{CC} = 3.0 V	2.2	2.68	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}				
		I _O = 100 μA; V _{CC} = 1.65 V to 3.6 V	-	-	0.2	V
		I _O = 6 mA; V _{CC} = 1.65 V	-	0.11	0.3	V
		I _O = 12 mA; V _{CC} = 2.3 V	-	0.17	0.4	V
		I _O = 18 mA; V _{CC} = 2.3 V	-	0.25	0.6	V
		I _O = 12 mA; V _{CC} = 2.7 V	-	0.16	0.4	V
		I _O = 18 mA; V _{CC} = 3.0 V	-	0.23	0.4	V
		I _O = 24 mA; V _{CC} = 3.0 V	-	0.30	0.55	V
I _I	input leakage current	V _{CC} = 3.6 V; V _I = 3.6 V or GND	-	±0.1	±5	μA

Table 6. Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
I _{OZ}	OFF-state output current	V _I = V _{IH} or V _{IL} ; V _{CC} = 1.65 V to 3.6 V; V _O = 3.6 V or GND;	-	±0.1	±10	μA
I _{OFF}	power-off leakage supply	V _{CC} = 0 V; V _I or V _O = 0 V to 3.6 V	-	±0.1	±10	μA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = V _{CC} or GND; I _O = 0 A	-	0.2	10	μA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3.0 V to 3.6 V; V _I = V _{CC} – 0.6 V; I _O = 0 A	-	5	750	μA
C _I	input capacitance		-	3.5	-	pF

[1] All typical values are measured at V_{CC} = 3.3 V (unless stated otherwise) and T_{amb} = 25 °C.

10. Dynamic characteristics

Table 7. Dynamic characteristicsVoltages are referenced to GND (ground = 0 V). For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
t _{pd}	propagation delay	CP to Qn; see Figure 7 ^[2]				
		V _{CC} = 1.65 V to 1.95 V	1.0	3.1	6.4	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.3	3.9	ns
		V _{CC} = 2.7 V	1.0	2.5	3.6	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.5	3.6	ns
t _{en}	enable time	OE to Qn; see Figure 8 ^[2]				
		V _{CC} = 1.65 V to 1.95 V	1.0	3.2	6.4	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.6	4.5	ns
		V _{CC} = 2.7 V	1.0	3.2	4.6	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.4	4.0	ns
t _{dis}	disable time	OE to Qn; see Figure 8 ^[2]				
		V _{CC} = 1.65 V to 1.95 V	1.5	3.6	7.0	ns
		V _{CC} = 2.3 V to 2.7 V	1.0	2.3	4.4	ns
		V _{CC} = 2.7 V	1.5	2.9	4.4	ns
		V _{CC} = 3.0 V to 3.6 V	1.0	2.8	4.4	ns
t _w	pulse width	clock HIGH or LOW; see Figure 7				
		V _{CC} = 1.65 V to 1.95 V	3.8	1.1	-	ns
		V _{CC} = 2.3 V to 2.7 V	3.3	0.9	-	ns
		V _{CC} = 2.7 V	3.3	0.8	-	ns
		V _{CC} = 3.0 V to 3.6 V	3.3	1.2	-	ns

Table 7. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V). For test circuit see [Figure 10](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			Unit
			Min	Typ ^[1]	Max	
t _{su}	set-up time	Dn to CP; see Figure 9				
		V _{CC} = 1.65 V to 1.95 V	0.8	–0.1	-	ns
		V _{CC} = 2.3 V to 2.7 V	0.8	0.1	-	ns
		V _{CC} = 2.7 V	0.8	0.3	-	ns
t _h	hold time	Dn to CP; see Figure 9				
		V _{CC} = 1.65 V to 1.95 V	0.8	–0.1	-	ns
		V _{CC} = 2.3 V to 2.7 V	0.8	0.1	-	ns
		V _{CC} = 2.7 V	0.8	0.4	-	ns
f _{max}	maximum frequency	see Figure 7				
		V _{CC} = 2.3 V to 2.7 V	100	200	-	MHz
		V _{CC} = 2.7 V	100	200	-	MHz
		V _{CC} = 3.0 V to 3.6 V	150	300	-	MHz
C _{PD}	power dissipation capacitance	per flip-flop; V _I = GND to V _{CC} ; V _{CC} = 3.3 V ^[3]				
		outputs HIGH or LOW state	-	21	-	pF
		outputs 3-state	-	13	-	pF

[1] Typical values are measured at T_{amb} = 25 °C

[2] t_{pd} is the same as t_{PHL} and t_{PLH}.

t_{en} is the same as t_{PZH} and t_{PZL}.

t_{dis} is the same as t_{PHZ} and t_{PLZ}.

[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

P_D = C_{PD} × V_{CC}² × f_i × N + Σ(C_L × V_{CC}² × f_o) where:

f_i = input frequency in MHz; f_o = output frequency in MHz

C_L = output load capacitance in pF

V_{CC} = supply voltage in Volts

N = number of inputs switching

Σ(C_L × V_{CC}² × f_o) = sum of the outputs

11. Waveforms

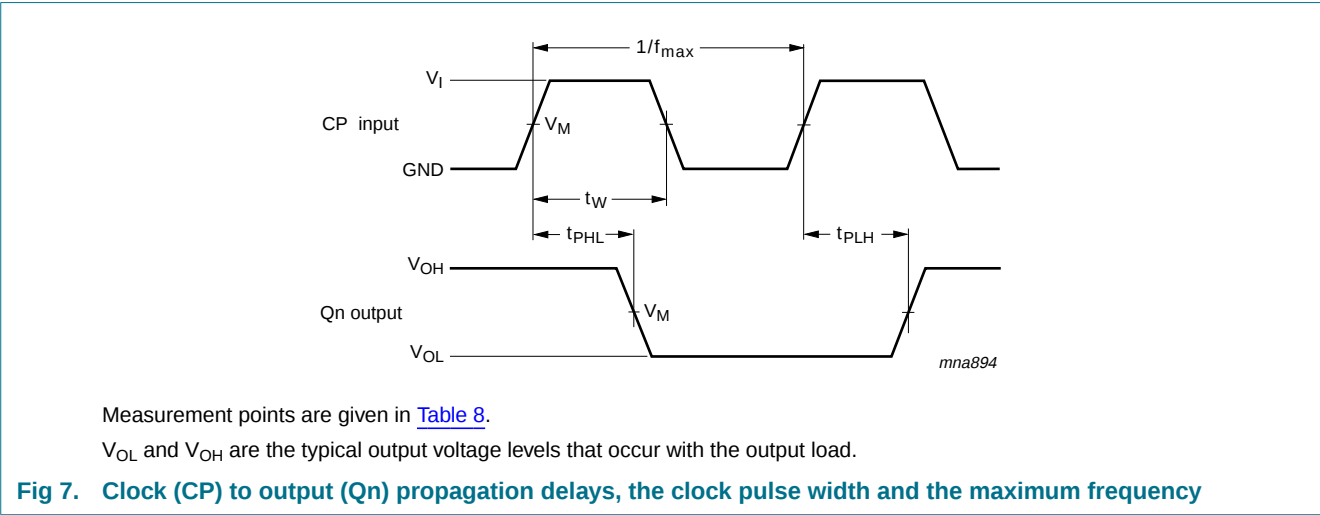
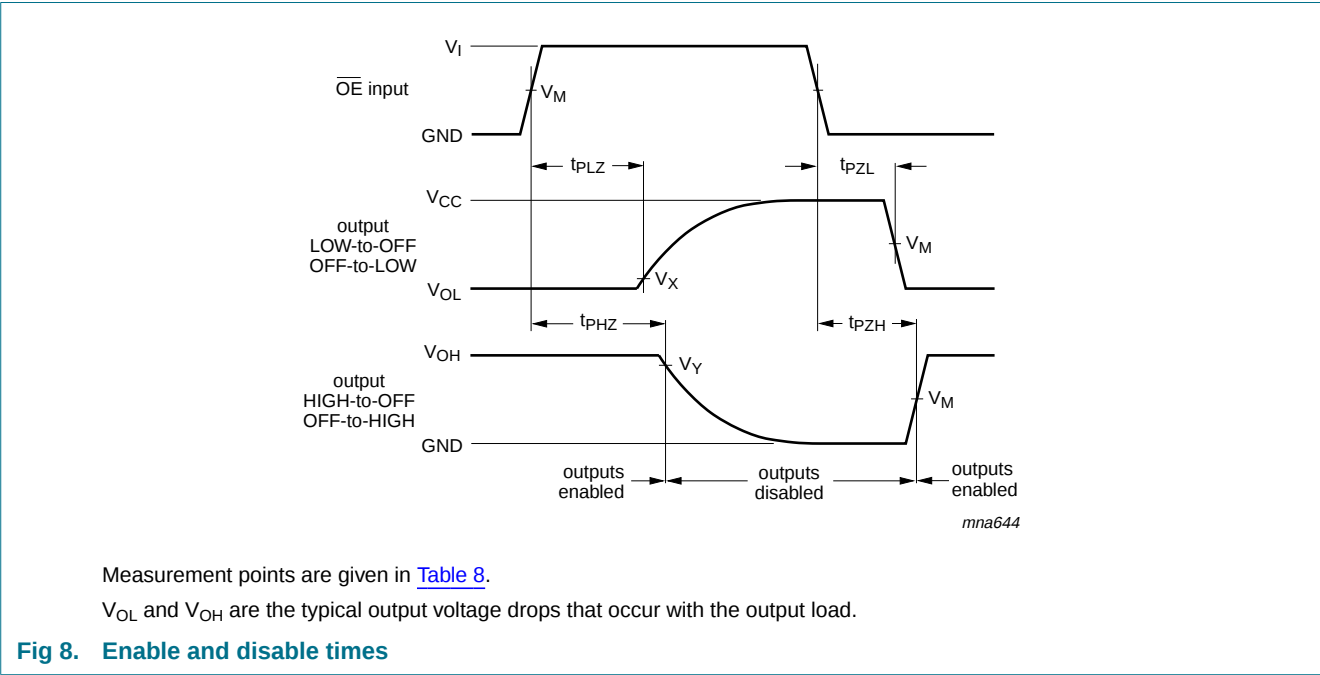
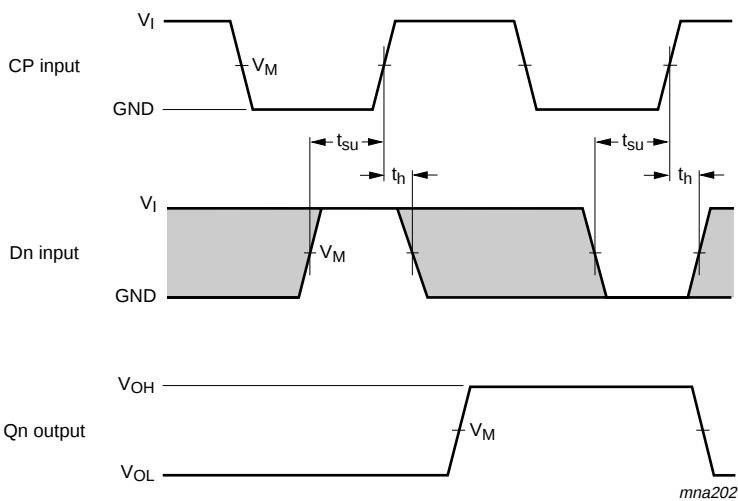


Table 8. Measurement points

Supply voltage	Input	Output		
V_{CC}	V_M	V_M	V_x	V_y
1.65 V to 1.95 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15\text{ V}$	$V_{OH} - 0.15\text{ V}$
2.3 V to 2.7 V	$0.5V_{CC}$	$0.5V_{CC}$	$V_{OL} + 0.15\text{ V}$	$V_{OH} - 0.15\text{ V}$
2.7 V	2.7 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$
3.0 V to 3.6 V	2.7 V	1.5 V	$V_{OL} + 0.3\text{ V}$	$V_{OH} - 0.3\text{ V}$





Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are the typical output voltage drops that occur with the output load.
The shaded areas indicate when the input is permitted to change for predicable output performance.

Fig 9. Data set-up and hold times for the Dn input to the CP input

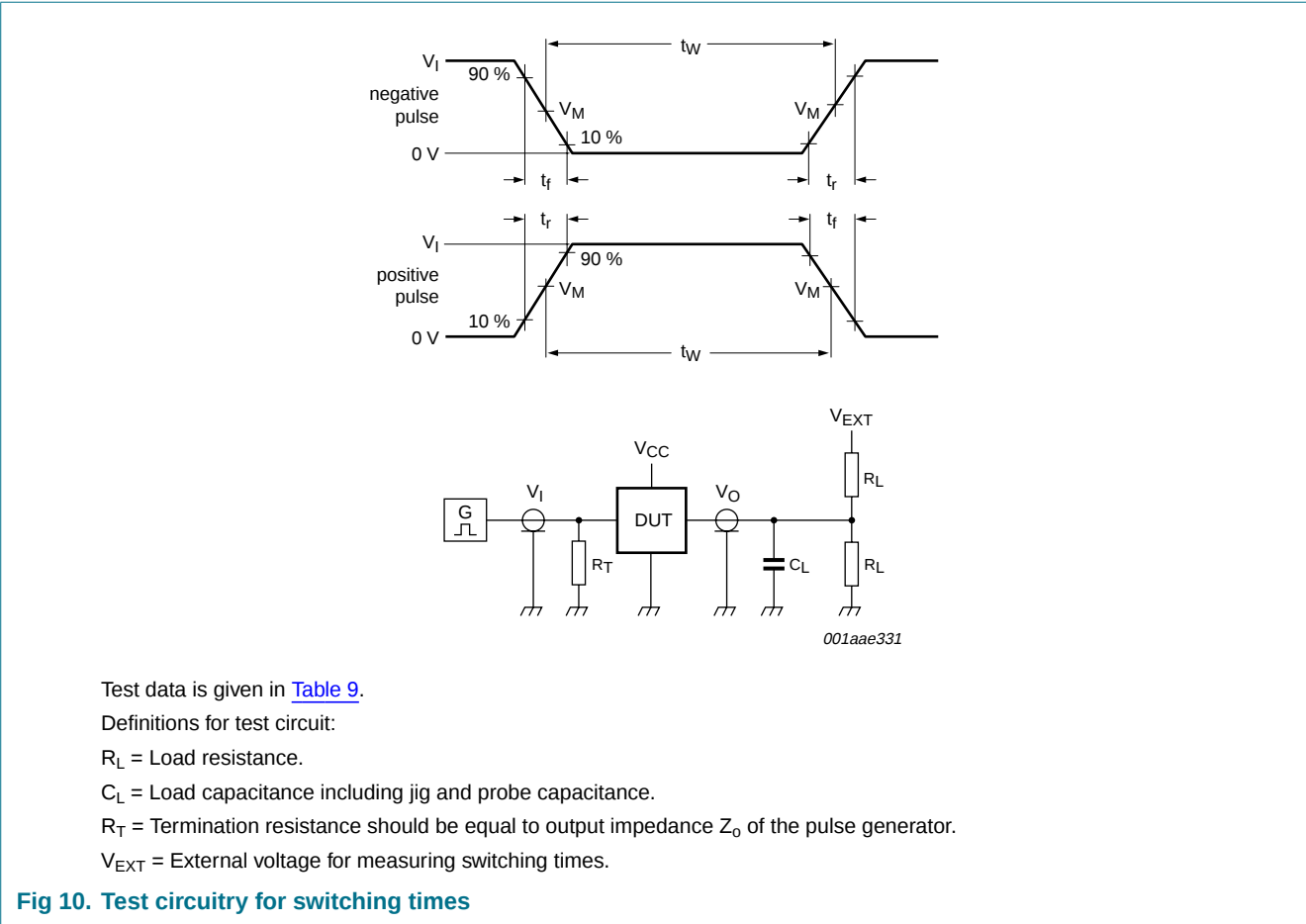


Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
1.65 V to 1.95 V	V_{CC}	≤ 2.0 ns	30 pF	1 k Ω	open	$2V_{CC}$	GND
2.3 V to 2.7 V	V_{CC}	≤ 2.0 ns	30 pF	500 Ω	open	$2V_{CC}$	GND
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6 V	GND
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open	6 V	GND

12. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm SOT163-1

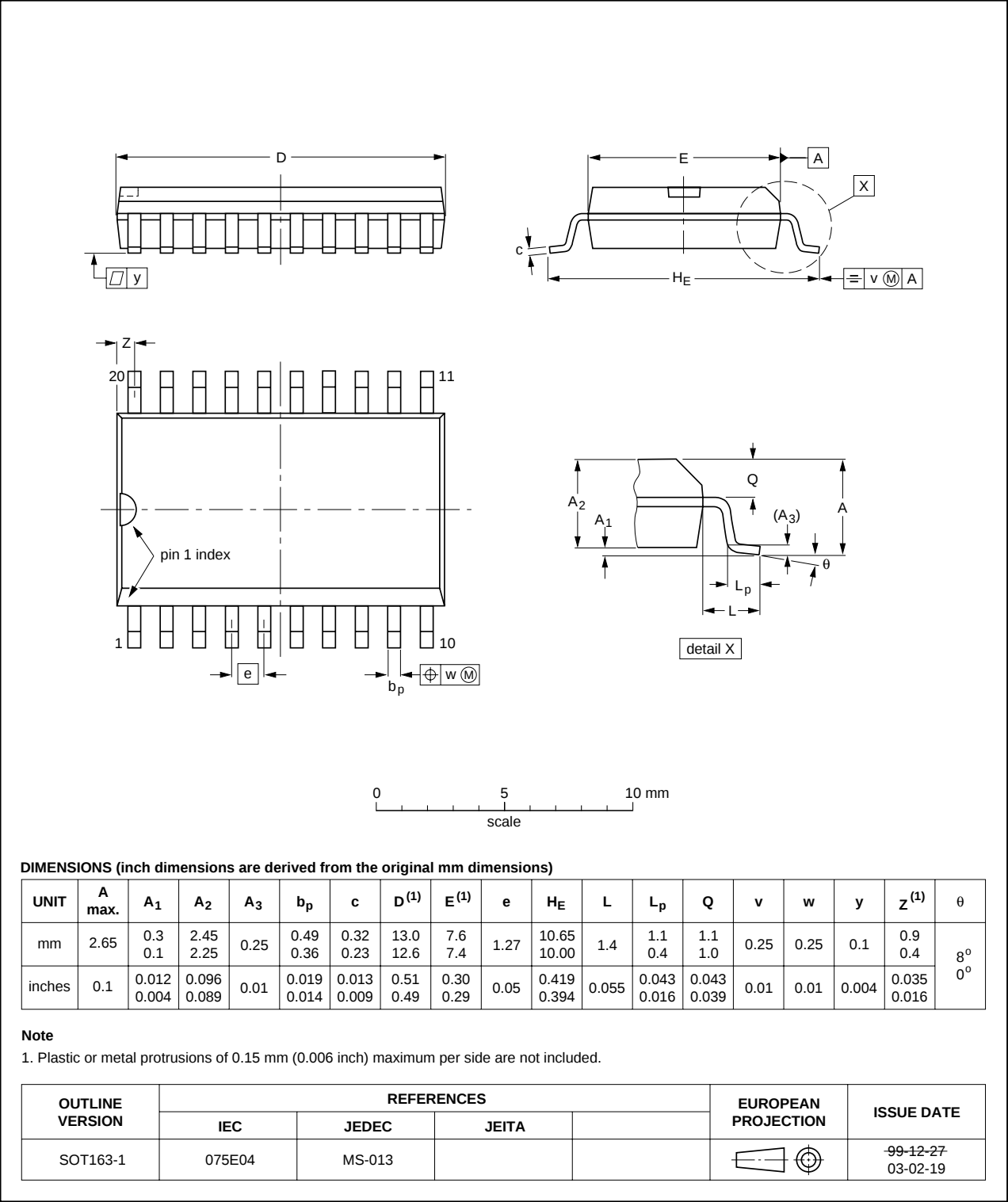


Fig 11. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

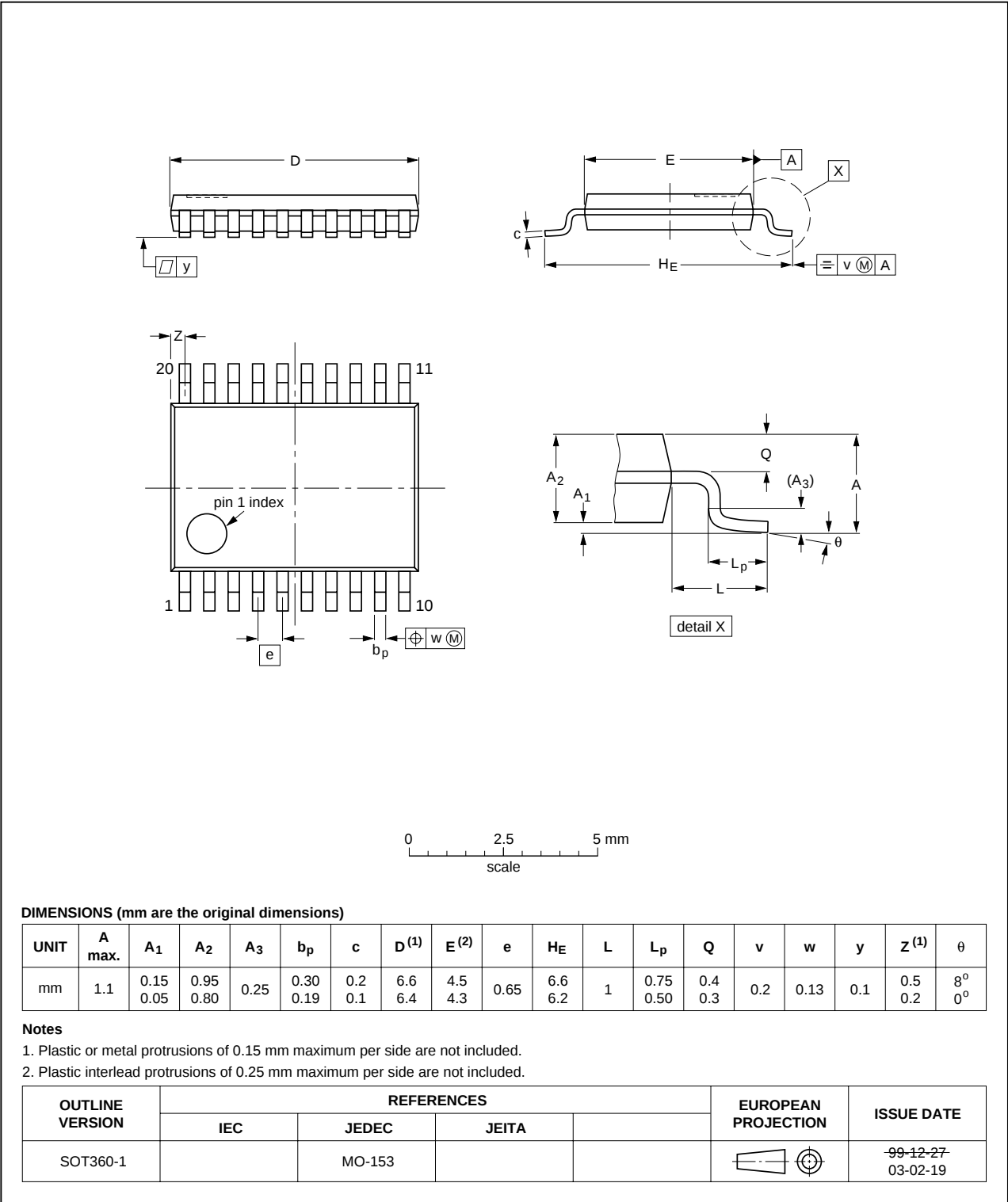


Fig 12. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

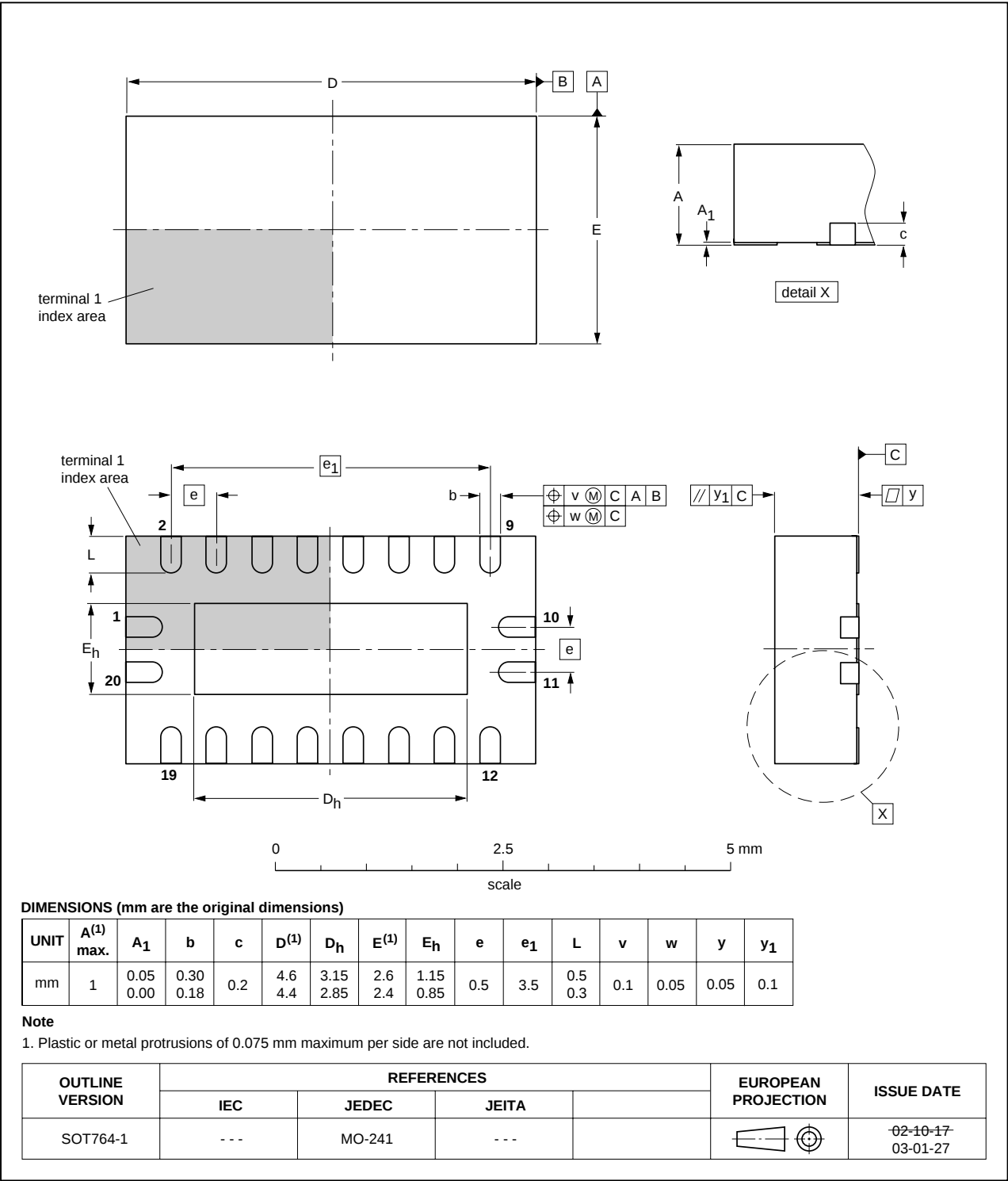


Fig 13. Package outline SOT764-1 (DHVQFN20)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVC374_2	20071017	Product data sheet	-	74ALVC374_1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Section 3: DHVQFN20 package added. • Section 7: derating values added for DHVQFN20 package. • Section 12: outline drawing added for DHVQFN20 package.			
74ALVC374_1	20020227	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

15.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

15.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or

malfunction of a NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

15.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

16. Contact information

For additional information, please visit: <http://www.nxp.com>

For sales office addresses, send an email to: salesaddresses@nxp.com

17. Contents

1 General description 1

2 Features 1

3 Ordering information 2

4 Functional diagram 2

5 Pinning information 4

5.1 Pinning 4

5.2 Pin description 4

6 Functional description 5

7 Limiting values 5

8 Recommended operating conditions 6

9 Static characteristics 6

10 Dynamic characteristics 7

11 Waveforms 9

12 Package outline 12

13 Abbreviations 15

14 Revision history 15

15 Legal information 16

15.1 Data sheet status 16

15.2 Definitions 16

15.3 Disclaimers 16

15.4 Trademarks 16

16 Contact information 16

17 Contents 17



Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

NXP:

[74ALVC374D](#) [74ALVC374D-T](#) [74ALVC374PW-T](#)